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Title of Invention:

PLASTIC INTEGRATED CIRCUIT  
PACKAGE AND METHOD AND  
LEADFRAME FOR MAKING THE  
PACKAGE

First Named Inventor:

THOMAS GLENN

Domestic/Foreign Application:

Domestic Application

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## TRANSMITTAL

Electronic Version v1.1  
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Title of Invention	PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND LEADFRAME FOR MAKING THE PACKAGE	
<p>Application Number: 10/626150 Date: 2003-07-24 First Named Applicant: THOMAS P.  Confirmation Number: 9302 Attorney Docket Number: AMKOR007C2</p>		
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Submitted by:	Elec. Sign.	Sign. Capacity
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney
Documents being submitted us-ids	Files ids2-usidst.xml us-ids.dtd us-ids.xsl	
Comments		



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18  
Stylesheet Version v18.0

Title of Invention	PLASTIC INTEGRATED CIRCUIT PACKAGE AND LEADFRAME FOR MAKING THE PACKAGE						
Application Number:	10/626150						
Confirmation Number:	9302						
First Named Applicant:	THOMAS GLENN						
Attorney Docket Number:	AMKOR007C2						
Art Unit:	2815						
Search string:	( 5216278 or 5218231 or 5221642 or 5250841 or 5252853 or 5258094 or 5266834 or 5273938 or 5277972 or 5278446 or 5279029 or 5281849 or 5294897 or 5327008 or 5332864 or 5335771 or 5336931 or 5343076 or 5358905 or 5365106 or 5381042 or 5391439 or 5406124 or 5410180 or 5414299 or 5417905 or 5424576 or 5428248 or 5435057 or 5444301 or 5452511 or 5454905 or 5474958 or 5484274 or 5493151 or 5508556 or 5517056 or 5521429 or 5528076 or 5534467 or 5539251 or 5543657 or 5544412 or 5545923 or 5581122 or 5592019 or 5592025 or 5594274 or 5595934 or 5604376 ).pn.						
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<p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p>							
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Signature

Examiner Name	Date